



FORM PTO-1449
LIST OF PATENTS AND
APPLICANT'S INFORMATION AND ASSURE STATEMENT

ATTORNEY DOCKET NO.: 26967-CON

SERIAL NO.: 10/647,674

FILING DATE: August 25, 2003

APPLICANT: AMMAR

EXAMINER: S. CLARK ART UNIT: ~~2815~~ 2823

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

| EXAMINER INITIALS | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUB CLASS | FILING IF APPROPRIATE |
|----------------------|----|--------------------|------|------|-------|--------------|--------------------------|
| | AA | | | | | | |
| | AB | | | | | | |
| | AC | | | | | | |
| | AD | | | | | | |
| | AE | | | | | | |
| | AF | | | | | | |
| | AG | | | | | | |
| | AH | | | | | | |
| | AI | | | | | | |
| | AJ | | | | | | |
| | AK | | | | | | |
| | AL | | | | | | |
| | AM | | | | | | |

FOREIGN PATENT DOCUMENTS

| | | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUB CLASS | TRANSLATION Yes - No |
|-----------|----|--------------------|------------|---------|--------|--------------|-------------------------|
| <i>an</i> | AN | 02/23674 | 21.03.2002 | WO | H01Q21 | 00 | / |
| <i>ao</i> | AO | 0 961 322 | 01.12.1999 | EP | H01L23 | 66 | |
| <i>ap</i> | AP | 0 491 161 | 12.11.1991 | EP | H01L23 | 538 | |
| | AQ | | | | | | |

OTHER ART

(Including Author, Title, Date, Pertinent Pages, etc.)

| | | | |
|-----------|----|--|---|
| <i>ar</i> | AR | | Prabhu et al., "Co-Fired Ceramic on Metal Multichip Modules For Advanced Military Packaging," Aerospace and Electronics Conference, Proceedings of the IEEE, May 24, 1993, pp. 217-222. |
| | AS | | |

EXAMINER:

DATE CONSIDERED:

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; * Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.